

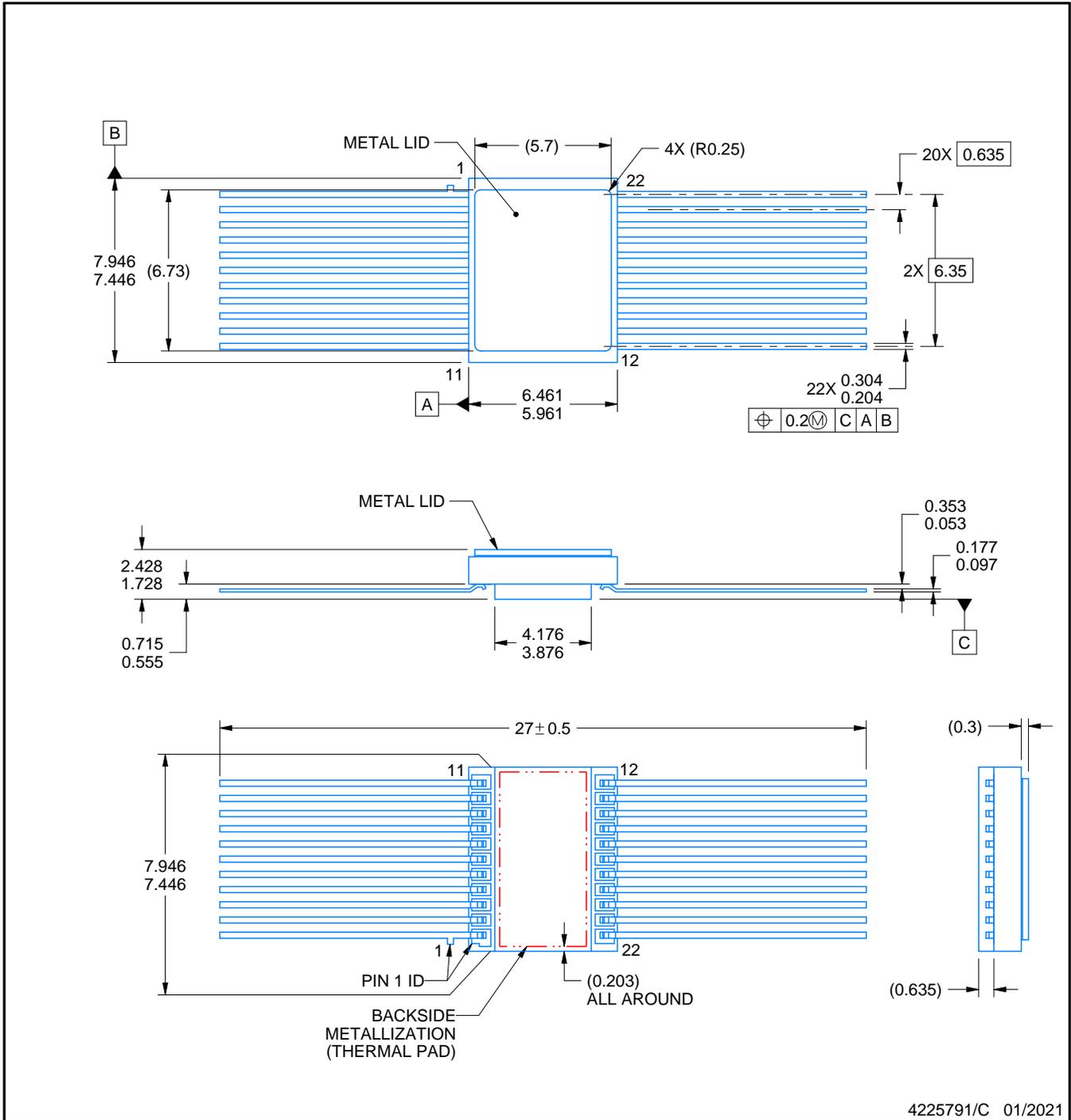
HFT0022A



PACKAGE OUTLINE

CFP - 2.428mm max height

CERAMIC FLATPACK



4225791/C 01/2021

NOTES:

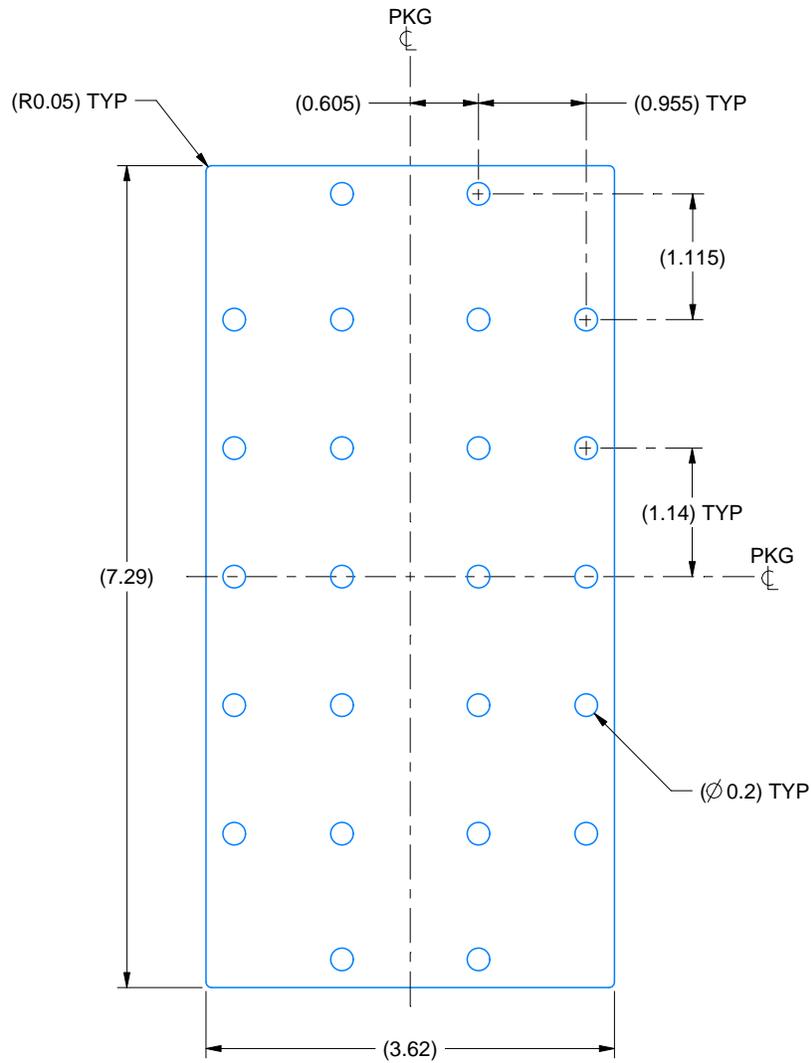
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid. The lid is not connected to any lead.
4. The leads are gold plated.
5. Metal lid is connected to backside metallization

EXAMPLE BOARD LAYOUT

HFT0022A

CFP - 2.428mm max height

CERAMIC FLATPACK



HEATSINK LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:15X

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REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2186323	03/13/2020	R. RAZAK / ANIS FAUZI
B	ADD LAND PATTERN VIEW / SHEET	2190485	10/22/2020	R. RAZAK / ANIS FAUZI
C	UPDATE TOTAL LEAD LENGTH TO 27 ± 0.5	2192775	01/28/2021	R. RAZAK / ANIS FAUZI

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